

Abstract of the Disclosure

5 A multiple cure adhesive (204) is used to secure a circuit substrate (104) to an underlying rigid surface (106). The adhesive is screen printed on the underlying surface. A first cure is then applied to the adhesive to at least partially cure the adhesive and to make the adhesive tacky. The circuit substrate is mounted on the tacky adhesive and a second cure is applied to the adhesive to firmly secure the circuit substrate to the housing.

10 By screen printing the adhesive on the underlying surface, the process of mounting a circuit substrate on a rigid surface can be completely automated, providing cost saving and waste reduction.